	Туре	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	‡	predetermined with pressure	USPA T; US-P GPUB	2003/05/0 3 14:13
2	BRS	L2	339	(transfer adj molding) and (semiconductor and leadframe)		2003/05/0 3 14:13
3	BRS	L3	4	1 and 2	USPA T; US-P GPUB	2003/05/0 3 14:13
4	BRS	L4	1432	264/272.11,272.13,272 .14,272.15,272.17,328 .4,328.5.ccls.	USPA T; US-P GPUB	2003/05/0 3 14:15
5	BRS	L5	87	1 and 4		2003/05/0 3 14:46
6	BRS	L6	35610	air adj gap	USPA T; US-P GPUB	2003/05/0 3 14:46
7	BRS	L8	208	mold adj vent	USPA T; US-P GPUB	2003/05/0 3 14:47
8	BRS	L10	95	vent and 14		2003/05/0 3 14:47
9	BRS	L9	9	4 and 8	USPA T; US-P GPUB	2003/05/0 3 14:47
10	BRS	L7	18	4 and 6	USPA T; US-P GPUB	2003/05/0 3 14:51